



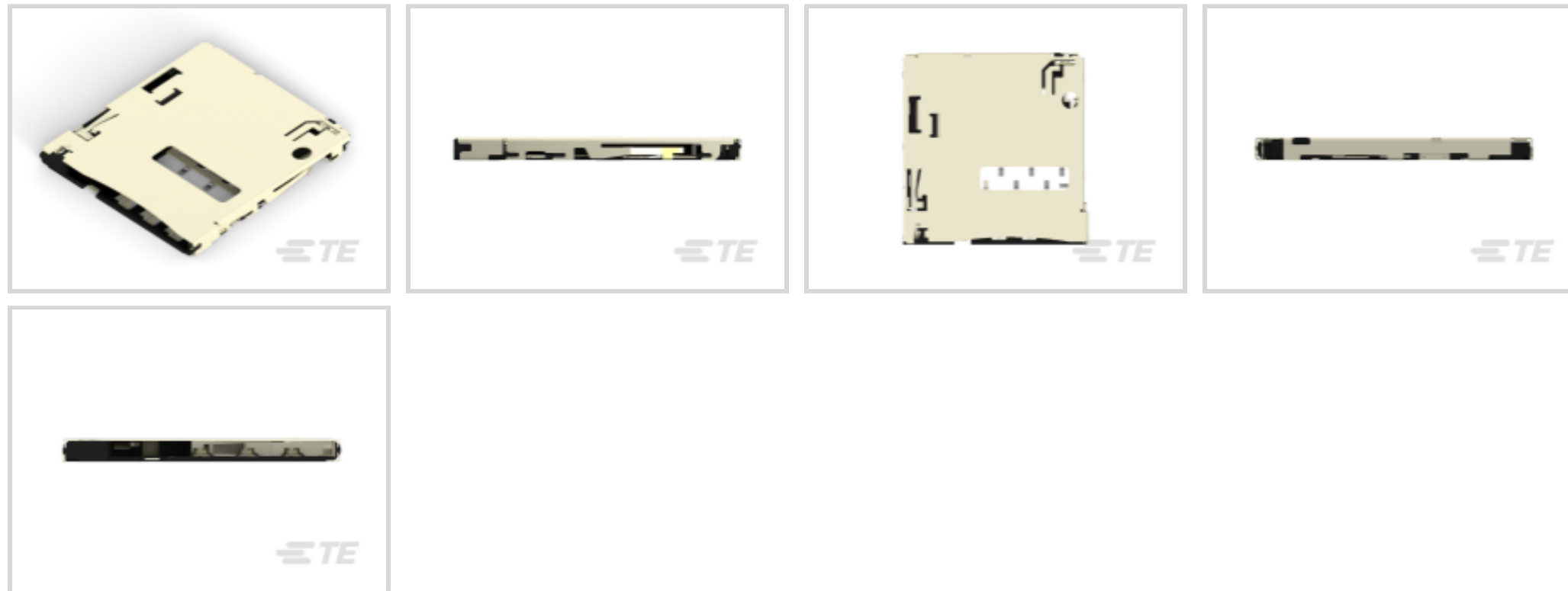
SIM Connectors

TE Internal #: 2229333-2

3FF SIM, Push-Push Type, 6 Position, 6 Loaded Positions, Signal, -30 – 85 °C [-22 – 185 °F], SIM Connectors, SIM Card Connectors

[View on TE.com >](#)

Connectors > PCB Connectors > Memory Card Connectors > SIM Card Connectors



Compatible Card: **3FF SIM**

SIM Card Product Type: **Push-Push Type**

Number of Positions: **6**

Number of Loaded Positions: **6**

Contact Current Rating (Max): **.5 A**

Features

Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
Card Stop	With
Compatible Card	3FF SIM
SIM Card Product Type	Push-Push Type

Configuration Features

Card Insertion Style	Normal Insertion
Number of Positions	6
Number of Loaded Positions	6

Body Features

Primary Product Color	Black
Ejector Type	Push-Push

Contact Features

Contact Base Material	Copper Alloy
Contact Current Rating (Max)	.5 A



Termination Features

Termination Method to PCB	Surface Mount
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Mechanical Attachment

Connector Mounting Type	Board Mount
Mating Alignment	With

Housing Features

Centerline (Pitch)	2.54 mm[.1 in]
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Usage Conditions

Operating Temperature Range	-30 – 85 °C[-22 – 185 °F]
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Operation/Application

Circuit Application	Signal
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Packaging Features

Packaging Method	Tape
Packaging Quantity	1050

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC
Halogen Content	Low Bromine/Chlorine - Br and Cl < 900 ppm per homogenous material. Also BFR /CFR/PVC Free
Solder Process Capability	Not reviewed for solder process capability

Product Compliance Disclaimer

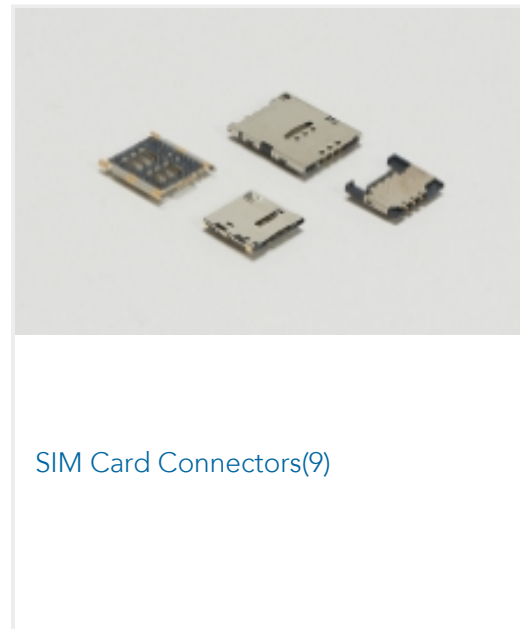
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous

materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

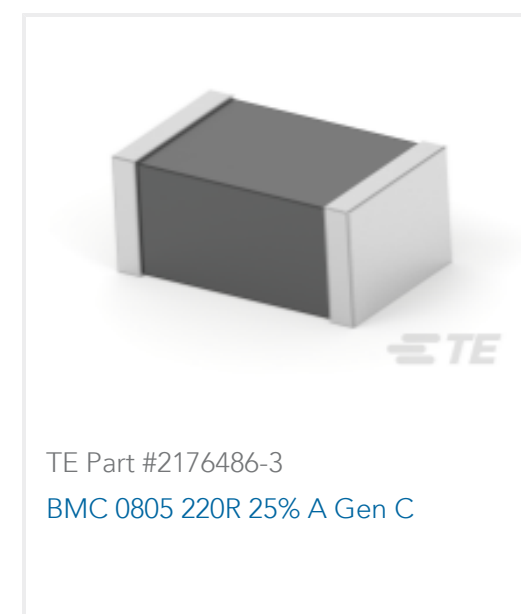
Compatible Parts



Also in the Series | SIM Connectors



Customers Also Bought





Documents

Product Drawings

[PUSH-PUSH MICRO SIM CONNECTOR SMT-2 TYPE](#)

English

CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG_CVM_CVM_2229333-2_F.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2229333-2_F.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2229333-2_F.3d_stp.zip](#)

English

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Product Specifications

[Product Specification](#)

English

[Product Specification](#)

English